

The marking on this product doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

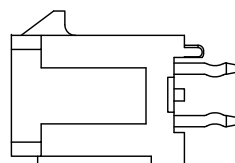
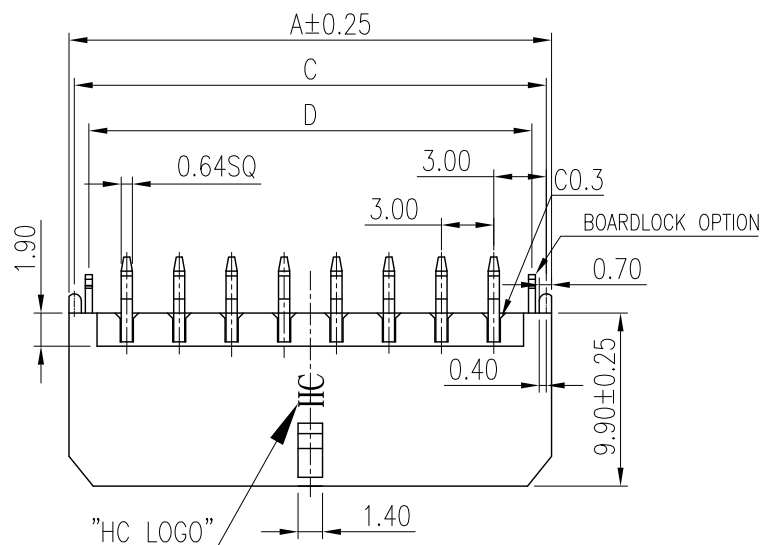


ORIGINAL

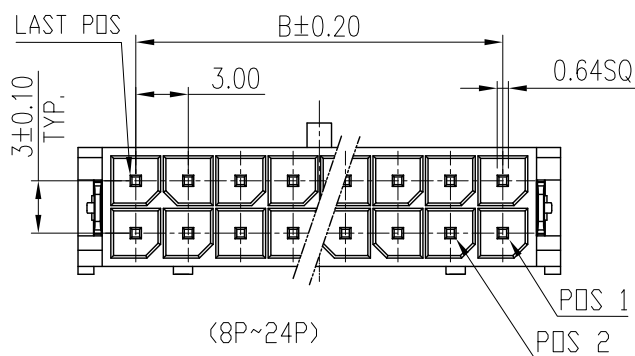


NOTE:

- 1.MATERIAL
INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR BLACK
CONTACT MATERIAL: HIGH PERFORMANCE COPPER ALLOY.
BOARDLOCK: COPPER ALLOY.
- 2.FINISH:
CONTACT: SELECTIVE PLATING. ;
SOLDERING AREA: MATTE TIN 100u" MIN. OR GOLD PLATING;
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN.OVERALL.
BOARDLOCK:
MATTE TIN 100u" MIN. PLATING;
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN.OVERALL.
- 4.THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS
MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
- 5.APPLICABLE P.C.BOARD THICKNESS: 1.60mm
- 6.PRODUCT SPECIFICATION REFER TO : PS-7528
- 7.PACKING MUST BE PER AMPHENOL PACKING SPECIFICATION
- 8.TO ENSURE CURRENT RATING CAPABILITY, AMPHENOL HIGH CURRENT PART
NUMBERS IN THE CHART ARE RECOMMENDED.
- (G88MPH CABLE HOUSING SERIES WITH G88MPC CABLE TERMINAL SERIES)



WITHOUT BOARDLOCK



PART NO. G88MPXX1XXEU

No. OF CIRCUIT—

BOARDLOCK OPTION

K: WITH BOARDLOCK

M: WITHOUT BOARDLOCK

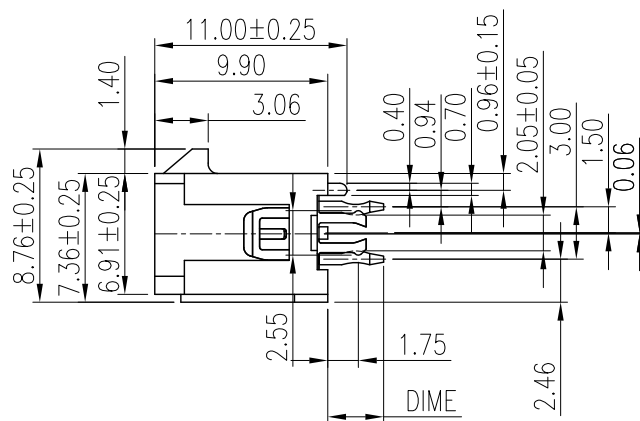
— INSULATOR,/ DIM E

1: LCP(NATURAL),/3.20±0.25

2: LCP (BLACK), $/3.20 \pm 0.25$

5: LCP(NATURAL),/2.80 $\begin{smallmatrix} +0.25 \\ -0.00 \end{smallmatrix}$

6: LCP (BLACK), /2.80 $\begin{smallmatrix} +0.25 \\ -0.00 \end{smallmatrix}$



WITH BOARDLOCK

POS	A	B	C	D
02	6.60		6.00	4.3
04	9.60	3.00	9.00	7.3
06	12.60	6.00	12.00	10.3
08	15.60	9.00	15.00	13.3
10	18.60	12.00	18.00	16.3
12	21.60	15.00	21.00	19.3
14	24.60	18.00	24.00	22.3
16	27.60	21.00	27.00	25.3
18	30.60	24.00	30.00	28.3
20	33.60	27.00	33.00	31.3
22	36.60	30.00	36.00	34.3
24	39.60	33.00	39.00	37.3

TOLERANCE		APPROVALS		DATE		TITLE G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)		Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation			
X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10		DRAWN	Aqua Chou	09/13/2016							
		CHECKED	Roger Tsai	09/13/2016							
		APPROVED	Roger Tsai	09/13/2016							
ANGULAR ±1°							UNIT mm	SIZE A3	PART No. G88MPXX1XXXEU		
UNLESS OTHERWISE SPECIFIED		DWG TYPE CUST DWG		PROJECT CODE PHD			SCALE NA	SHEET 1 OF 4	DWG No. G88MPXX1XXXEU		REV. B

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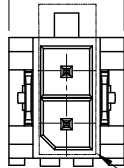


ORIGINAL



REVISIONS					
SYM	ECN No.	DESCRIPTION	DATE	APPROVED	
A	NE-14124	RELEASE FOR RoHS	06/24/2014	Arron Lin	
B	NE-16211	ADDED LCP NATURAL/BOARDLOCK/TAIL OPTION	09/13/2016	Roger Tsai	

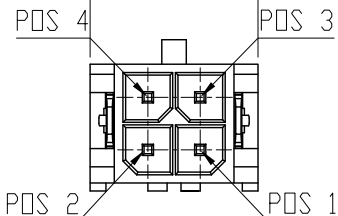
6.60±0.25



DETAIL D

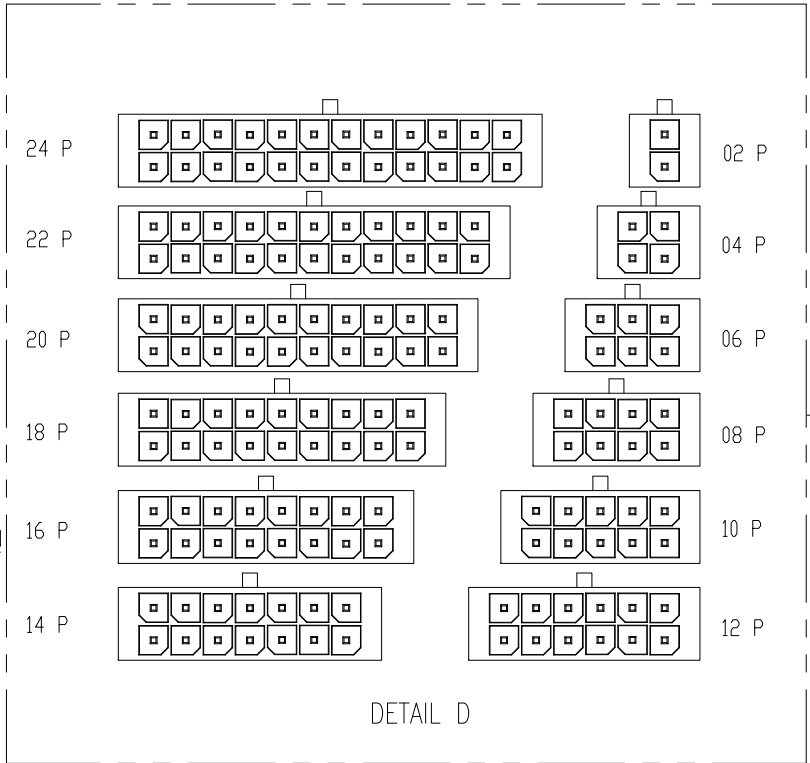
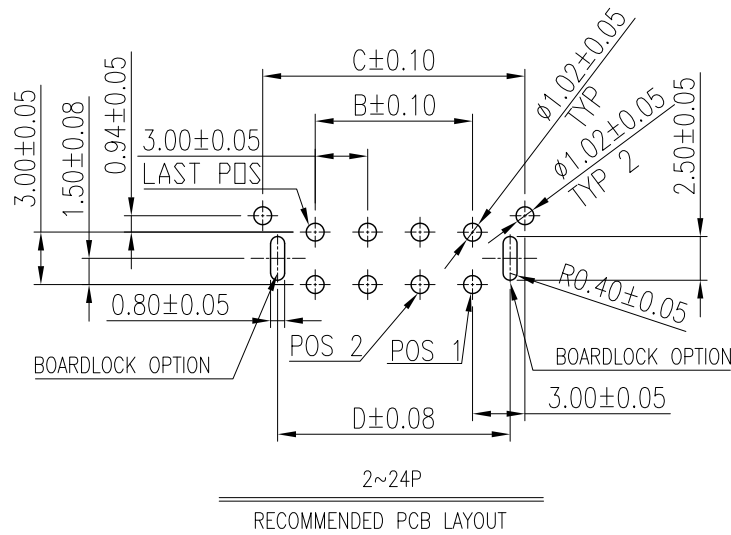
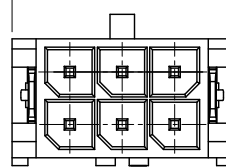
(2X1POS)

9.60±0.25



(2X2POS)

12.60±0.25



TOLERANCE		APPROVALS		DATE	TITLE G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)		Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation		
X.		DRAWN	Aqua Chou	09/13/2016					
X.X	±0.30	CHECKED	Roger Tsai	09/13/2016					
X.XX	±0.20	APPROVED	Roger Tsai	09/13/2016					
X.XXX	±0.10								
ANGULAR ±1°						UNIT mm	SIZE A3	PART No. G88MPXX1XXXEU	
UNLESS OTHERWISE SPECIFIED		DWG TYPE CUST DWG		PROJECT CODE PHD		SCALE NA	SHEET 2 OF 4	DWG No. G88MPXX1XXXEU	REV. B

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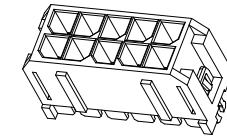


ORIGINAL

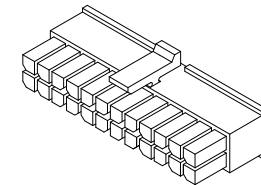


REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-14124	RELEASE FOR RoHS	06/24/2014	Arron Lin
B	NE-16211	ADDED LCP NATURAL/BOARDLOCK/TAIL OPTION	09/13/2016	Roger Tsai

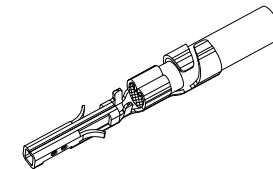
POS.	BOARD-MOUNT P/N	CABLE HOUSING P/N	CABLE TERMINAL P/N	AWG NO.	PLATING OPTIONS
02	G88MP021XXXEU	G88MPH0222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
04	G88MP041XXXEU	G88MPH0422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
06	G88MP061XXXEU	G88MPH0622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
08	G88MP081XXXEU	G88MPH0822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
10	G88MP101XXXEU	G88MPH1022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
12	G88MP121XXXEU	G88MPH1222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
14	G88MP141XXXEU	G88MPH1422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
16	G88MP161XXXEU	G88MPH1622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
18	G88MP181XXXEU	G88MPH1822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
20	G88MP201XXXEU	G88MPH2022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
22	G88MP221XXXEU	G88MPH2222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
24	G88MP241XXXEU	G88MPH2422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD



AMPHENOL BOARD-MOUNT



AMPHENOL CABLE HOUSING



AMPHENOL CABLE TERMINAL

NOTE:
TO ENSURE CURRENT RATING CAPABILITY,
AMPHENOL HIGH CURRENT PART NUMBERS IN THE
CHART ARE RECOMMENDED.
(G88MPH CABLE HOUSING SERIES WITH G88MPC
CABLE TERMINAL SERIES)

TOLERANCE		APPROVALS		DATE	TITLE G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)	Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation				
X.		DRAWN	Aqua Chou	09/13/2016						
X.X	±0.30	CHECKED	Roger Tsai	09/13/2016						
X.XX	±0.20									
X.XXX	±0.10	APPROVED	Roger Tsai	09/13/2016						
ANGULAR ±1°						UNIT mm	SIZE A3	PART No. G88MPXX1XXXEU		
UNLESS OTHERWISE SPECIFIED		DWG TYPE CUST DWG	PROJECT CODE PHD			SCALE NA	SHEET 3 OF 4	DWG No. G88MPXX1XXXEU	REV. B	

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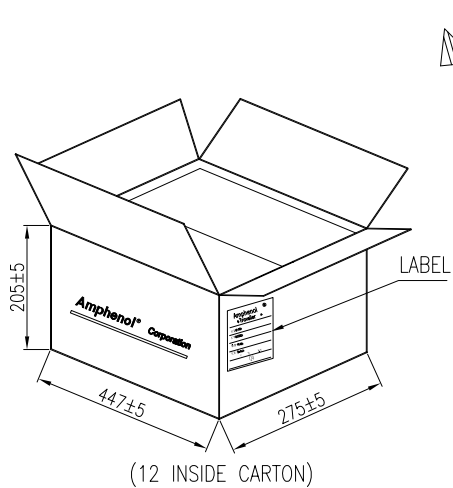
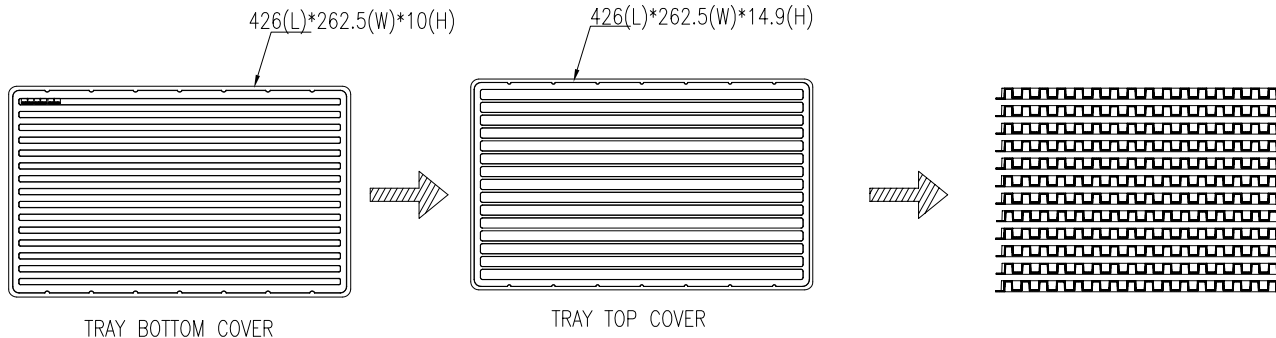
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ORIGINAL



REVISIONS			
SYM	ECN No.	DESCRIPTION	DATE
A	NE-14124	RELEASE FOR RoHS	06/24/2014
B	NE-16211	ADDED LCP NATURAL/BOARDLOCK/TAIL OPTION	09/13/2016
			APPROVED
			Arron Lin
			Roger Tsai



POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

- NOTE:
1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
 2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
 3. THICKNESS : 0.80±0.05mm.

TOLERANCE		APPROVALS		DATE		TITLE G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)			Amphenol® Amphenol Corporation Amphenol Taiwan Corporation				
X.		DRAWN		Aqua Chou								09/13/2016	
X.X ±0.30		CHECKED		Roger Tsai								09/13/2016	
X.XX ±0.20		APPROVED		Roger Tsai								09/13/2016	
X.XXX ±0.10													
ANGULAR ±1°													
UNLESS OTHERWISE SPECIFIED		DWG TYPE		PROJECT CODE				UNIT		SIZE		PART No.	
		CUST DWG		PHD				mm		A3		G88MPXX1XXXEU	
						SCALE		SHEET		DWG No.		REV.	
						NA		4 OF 4		G88MPXX1XXXEU		B	

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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